

A

A

B

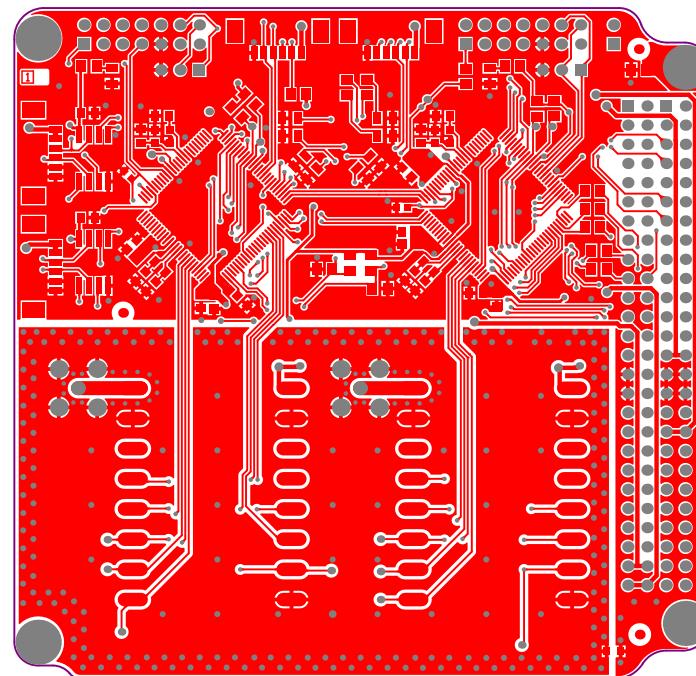
B

C

C

D

D



LAYER	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay	Solder Resist	0.010mm	3.5	
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Top Layer	Copper	0.035mm		
4	Dielectric		1.620mm	4.2	
5	Bottom Layer	Copper	0.035mm		
6	Bottom Solder	Solder Resist	0.010mm	3.5	
7	Bottom Overlay				

### Fabrication specifications:

- Copper base 10Z
- PCB Material: Prepeg FR4—Standard
- PCB Thickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Blue
- Vias: Force Complete Tenting
- Special: Stack-up (herein included)

### Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina	
Project: TTC2	
Layer: Top Layer      Board Edge	
Designed by: Andre M. P. Mattos	Project Code: TTC2
Date: 6/15/2021	Version: v0.1
	Size: A4

A

A

B

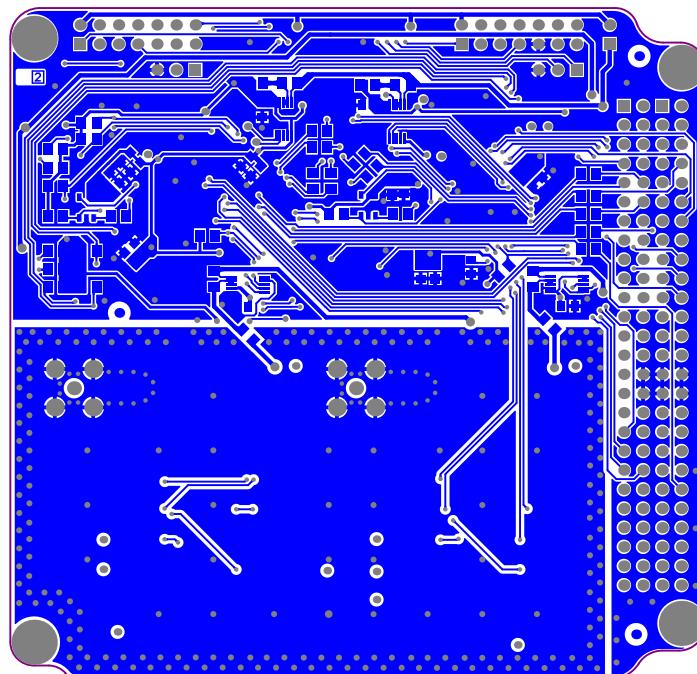
B

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D

D



LAYER	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Top Layer	Copper	0.035mm		
4	Dielectric		1.520mm	4.2	
5	Bottom Layer	Copper	0.035mm		
6	Bottom Solder	Solder Resist	0.010mm	3.5	
7	Bottom Overlay				

### Fabrication specifications:

- Copper base 10Z
- PCB Material: Prepeg FR4—Standard
- PCB Thickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Blue
- Vias: Force Complete Tenting
- Special: Stack-up (herein included)

### Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina	
Project: TTC2	
Layer: Bottom Layer Board Edge	
Designed by: Andre M. P. Mattos	
Date: 6/15/2021	Project Code: TTC2
Version: v0.1	Size: A4

A

A

B

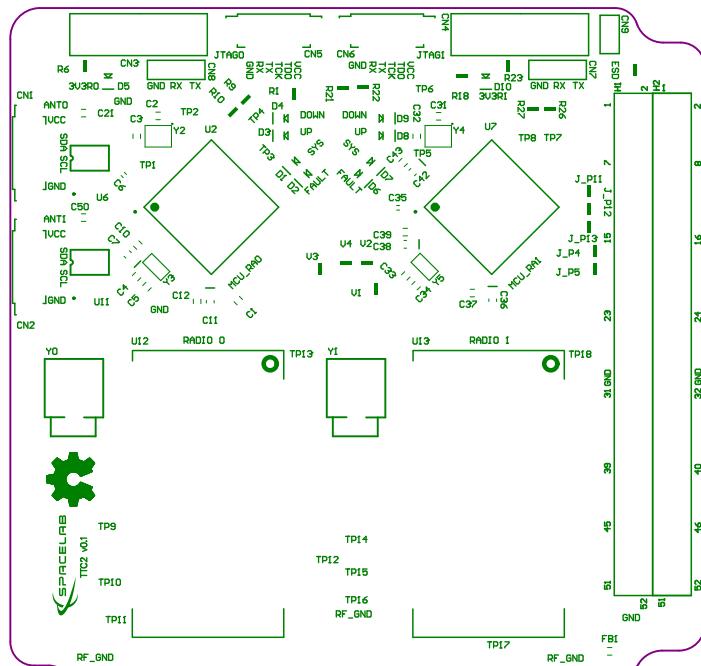
B

C

C

D

D



LAYER	NAME	MATERIAL	THICKNESS	CONSTANT	BOARD LAYER STACK
1	Top Overlay	Solder Resist	0.010mm	3.5	
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Top Layer	Copper	0.035mm		
4	Dielectric		1.520mm	4.2	
5	Bottom Layer	Copper	0.035mm		
6	Bottom Solder	Solder Resist	0.010mm	3.5	
7	Bottom Overlay				

### Fabrication specifications:

- Copper base 10Z
- PCB Material: Prepeg FR4—Standard
- PCB Thickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Blue
- Vias: Force Complete Tenting
- Special: Stack-up (herein included)

### Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina

Project: TTC2

Layer: Top Overlay Board Edge

Designed by: Andre M. P. Mattos

Date: 6/15/2021 Version: v0.1



Project Code: TTC2

Size: A4

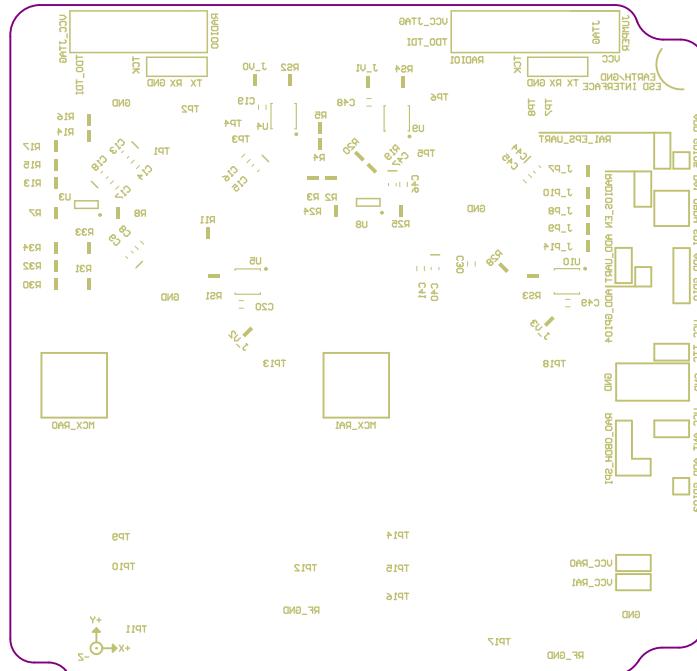
A

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Layer	Name	Material	Thickness	Constant	Board Layer	Stack
1	Top Overlay					
2	Top Solder	Solder Resist	0.010mm	3.5		
3	Top Layer	Copper	0.025mm			
4	Dielectric		1.520mm	4.2		
5	Bottom Layer	Copper	0.025mm			
6	Bottom Solder	Solder Resist	0.010mm	3.5		
7	Bottom Overlay					

Fabrication specifications:

- Copper base 1OZ:
  - PCB Material: Prepeg FR4—Standard
  - PCB Thickness: 1.6mm
  - PCB Surface: HASL (with lead)
  - Silkscreen Color: White (top and bottom)
  - Soldermask Color: Blue
  - Vias: Force Complete Tenting
  - Special: Stack-up (herein included)

## Assembly specifications:

- Solder composition: Include lead
  - Fiducials: 3 top and 3 bottom available
  - Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina	
Project: TTC2	
Layer: Bottom Overlay Board Edge	
Designed by: Andre M. P. Mattos	Project Code: TTC2
Date: 6/15/2021	Version: v0.1
	Size: A4

A

A

B

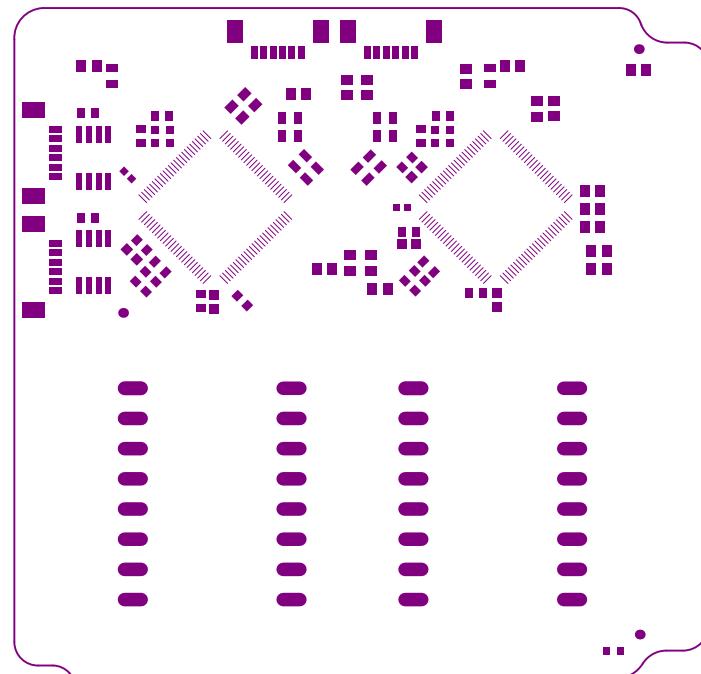
B

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C

D

D



LAYER	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Top Layer	Copper	0.035mm		
4	Dielectric		1.520mm	4.2	
5	Bottom Layer	Copper	0.035mm		
6	Bottom Solder	Solder Resist	0.010mm	3.5	
7	Bottom Overlay				

### Fabrication specifications:

- Copper base 10Z
- PCB Material: Prepeg FR4—Standard
- PCB Thickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Blue
- Vias: Force Complete Tenting
- Special: Stack-up (herein included)

### Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina



Project: TTC2

Layer: Top Paste      Board Edge

Project Code: TTC2

Designed by: Andre M. P. Mattos

Date: 6/15/2021      Version: v0.1

Size: A4

A

A

B

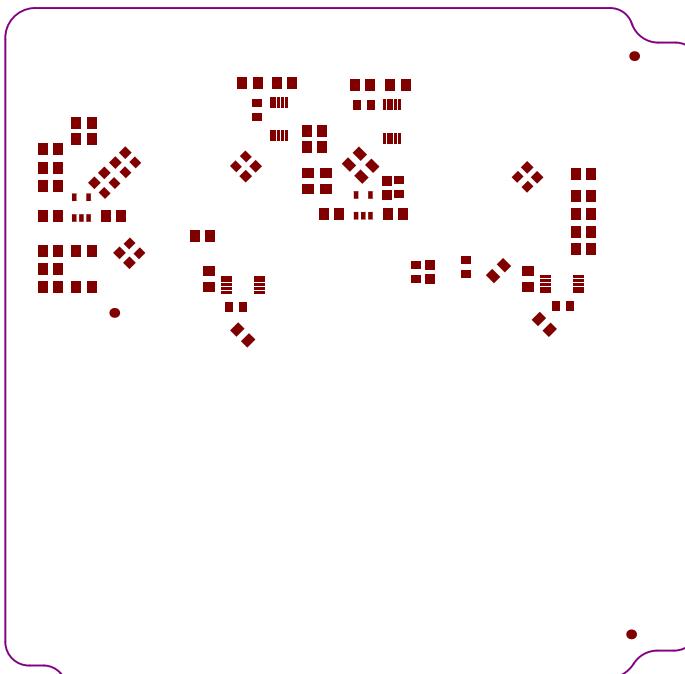
B

C

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D



LAYER	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Top Layer	Copper	0.035mm		
4	Dielectric		1.520mm	4.2	
5	Bottom Layer	Copper	0.035mm		
6	Bottom Solder	Solder Resist	0.010mm	3.5	
7	Bottom Overlay				

### Fabrication specifications:

- Copper base 10Z
- PCB Material: Prepeg FR4—Standard
- PCB Thickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Blue
- Vias: Force Complete Tenting
- Special: Stack-up (herein included)

### Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina



Project: TTC2

Layer: Bottom Paste Board Edge

Project Code: TTC2

Designed by: Andre M. P. Mattos

Size: A4

Date: 6/15/2021

Version: v0.1

A

A

B

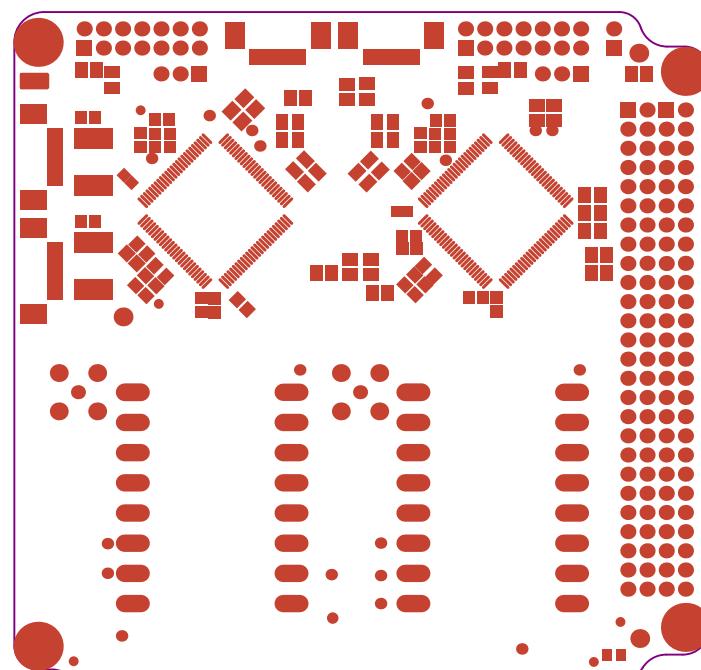
B

C

C

D

D



LAYER	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Top Layer	Copper	0.035mm		
4	Dielectric		1.520mm	4.2	
5	Bottom Layer	Copper	0.035mm		
6	Bottom Solder	Solder Resist	0.010mm	3.5	
7	Bottom Overlay				

### Fabrication specifications:

- Copper base 10Z
- PCB Material: Prepeg FR4—Standard
- PCB Thickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Blue
- Vias: Force Complete Tenting
- Special: Stack-up (herein included)

### Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina



Project: TTC2

Layer: Top Solder    Board Edge

Project Code: TTC2

Designed by: Andre M. P. Mattos

Date: 6/15/2021    Version: v0.1

Size: A4

A

A

B

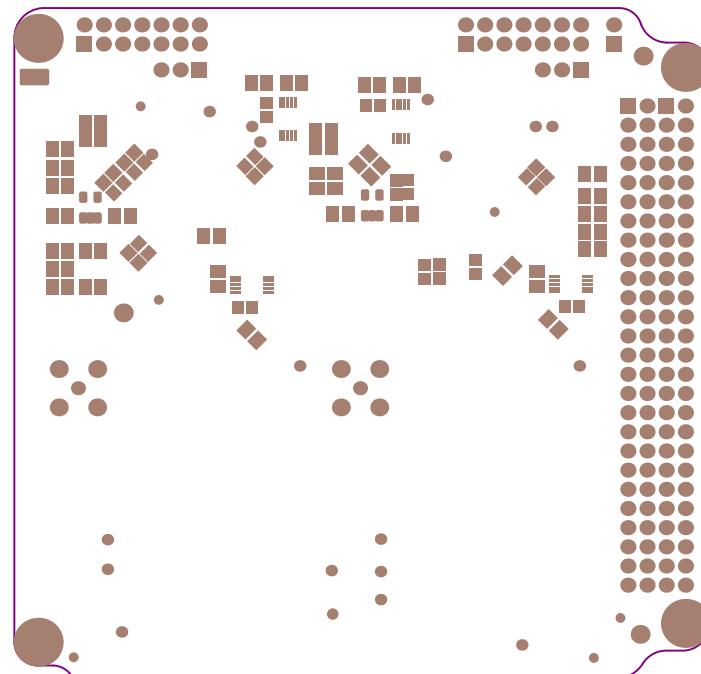
B

C

C

D

D



LAYER	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Top Layer	Copper	0.035mm		
4	Dielectric		1.520mm	4.2	
5	Bottom Layer	Copper	0.035mm		
6	Bottom Solder	Solder Resist	0.010mm	3.5	
7	Bottom Overlay				

### Fabrication specifications:

- Copper base 10Z:
- PCB Material: Prepeg FR4—Standard
- PCB Thickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Blue
- Vias: Force Complete Tenting
- Special: Stack-up (herein included)

### Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina



Project: TTC2

Layer: Bottom Solder Board Edge

Project Code: TTC2

Designed by: Andre M. P. Mattos

Size: A4

Date: 6/15/2021

Version: v0.1

A

A

B

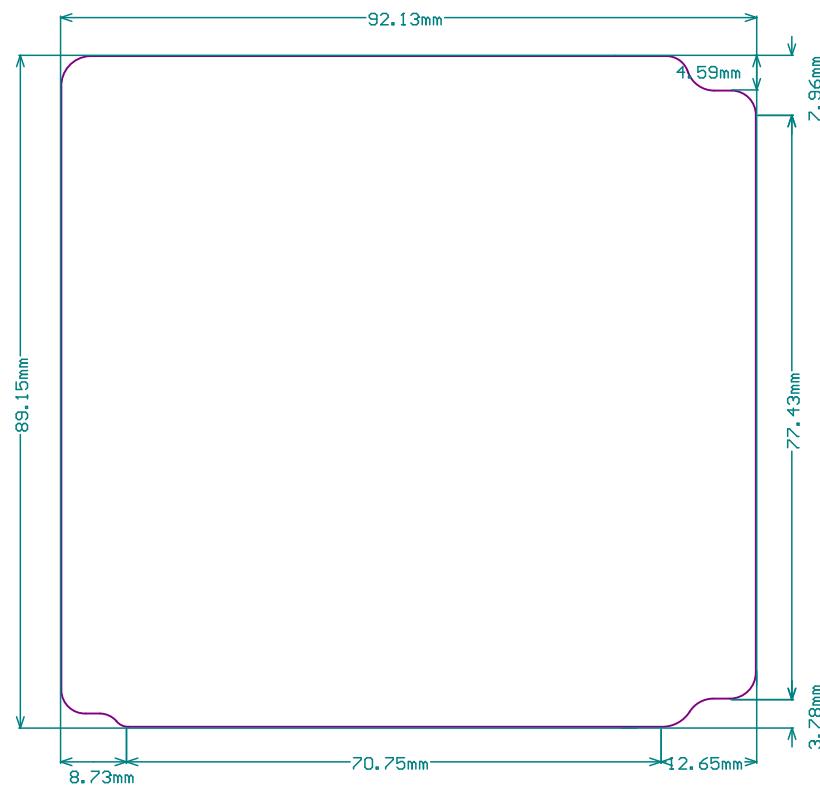
B

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D



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Top Layer	Copper	0.035mm		
4	Dielectric		1.520mm	4.2	
5	Bottom Layer	Copper	0.035mm		
6	Bottom Solder	Solder Resist	0.010mm	3.5	
7	Bottom Overlay				

### Fabrication specifications:

- Copper base 1OZ
- PCB Material: Prepeg FR4—Standard
- PCB Thickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Blue
- Vias: Force Complete Tenting
- Special: Stack-up (herein included)

### Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina

Project: TTC2

Layer: Dimension Board Edge

Designed by: Andre M. P. Mattos

Date: 6/15/2021 Version: v0.1

Project Code: TTC2

Size: A4



A

A

B

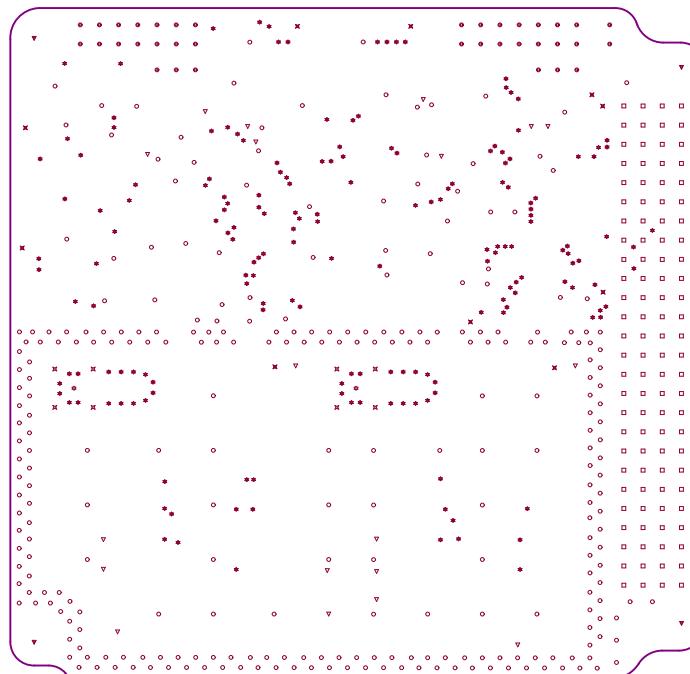
B

C

C

D

D



LAYER	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Top Layer	Copper	0.035mm		
4	Dielectric		1.520mm	4.2	
5	Bottom Layer	Copper	0.035mm		
6	Bottom Solder	Solder Resist	0.010mm	3.5	
7	Bottom Overlay				

Subset	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Wa/Pad
*	2	1.200mm (49.2mil)	PTH	Round	Top Layer - Bottom Layer	Pad
▼	4	3.200mm (125.9mil)	PTH	Round	Top Layer - Bottom Layer	Pad
▲	8	1.700mm (66.9mil)	PTH	Round	Top Layer - Bottom Layer	Pad
✖	10	0.800mm (31.7mil)	PTH	Round	Top Layer - Bottom Layer	Wa
✖	18	0.500mm (20.0mil)	PTH	Round	Top Layer - Bottom Layer	Wa
●	26	1.000mm (39.3mil)	PTH	Round	Top Layer - Bottom Layer	Pad
□	104	0.900mm (35.4mil)	PTH	Round	Top Layer - Bottom Layer	Pad
✖	184	0.300mm (11.8mil)	PTH	Round	Top Layer - Bottom Layer	Wa
○	294	0.400mm (15.7mil)	PTH	Round	Top Layer - Bottom Layer	Wa
648 Total						

## Fabrication specifications:

- Copper base 1OZ
- PCB Material: Prepeg FR4—Standard
- PCB Thickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Blue
- Vias: Force Complete Tenting
- Special: Stack-up (herein included)

## Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina

Project: TTC2

Layer: Drill Drawing Board Edge

Designed by: Andre M. P. Mattos

Date: 6/15/2021 Version: v0.1



Project Code: TTC2

Size: A4

A

A

B

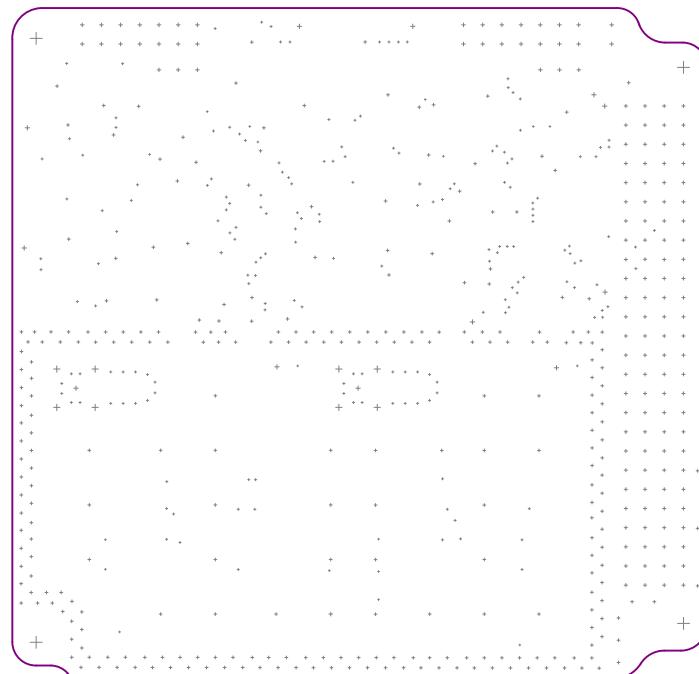
B

C

C

D

D



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Top Layer	Copper	0.035mm		
4	Dielectric		1.520mm	4.2	
5	Bottom Layer	Copper	0.035mm		
6	Bottom Solder	Solder Resist	0.010mm	3.5	
7	Bottom Overlay				

### Fabrication specifications:

- Copper base 10Z
- PCB Material: Prepeg FR4—Standard
- PCB Thickness: 1.6mm
- PCB Surface: HASL (with lead)
- Silkscreen Color: White (top and bottom)
- Soldermask Color: Blue
- Vias: Force Complete Tenting
- Special: Stack-up (herein included)

### Assembly specifications:

- Solder composition: Include lead
- Fiducials: 3 top and 3 bottom available
- Check BOM for not placed components

SpaceLab - Federal University of Santa Catarina

Project: TTC2

Layer: Drill Guide      Board Edge

 SPACELAB

Project Code: TTC2

Designed by: Andre M. P. Mattos

Date: 6/15/2021

Version: v0.1

Size: A4